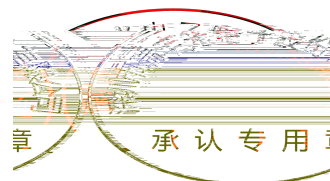
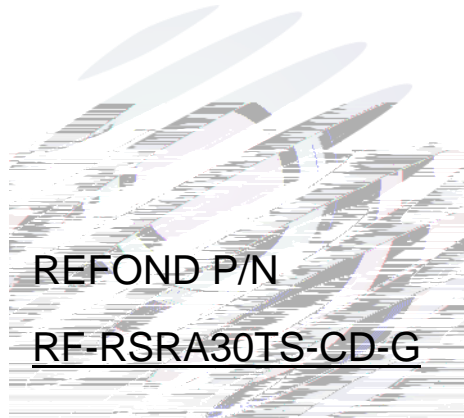
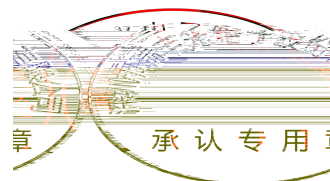
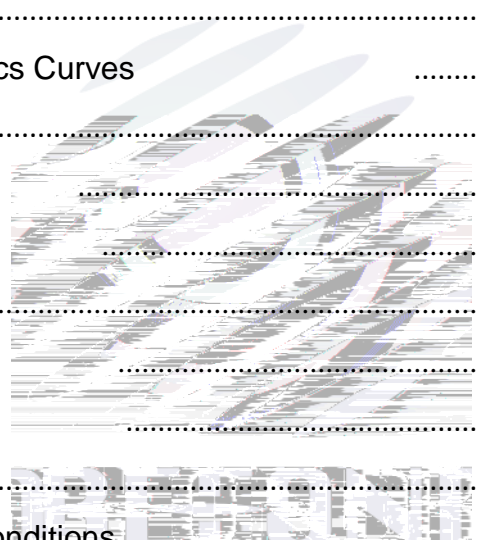


SPECIFICATION



Contents

1. Description	3
1.1 General Description	3
1.2 Features	3
1.3 Application	3
1.4 Package Dimension	4
1.5 Product Parameters	5
1.6 Bin Range Of Forward Voltage and Luminous Intensity and Dominant wavelength	
BIN	6
1.7 Typical Optical Characteristics Curves	7
2. Packaging	11
2.1 Packaging Specification	11
2.1.1 Carrier Tape Dimension	11
2.1.2 Reel Dimension	11
2.1.3 Label Form Specification	12
2.2 Moisture Resistant Packing	12
2.3 Cardboard Box	13
2.4 Reliability Test Items And Conditions	13
2.5 Criteria For Judging Damage	14
3. SMT Reflow Soldering Instructions SMT	15
3.1 SMT Reflow Soldering Instructions SMT	15
4. Handling Precautions	17
4.1 Handling Precautions	17



1. Description

1.1 General Description



The Red source color devices are made with AlGaInp on Substrate Light Emitting Diode .

Product Package:3.50mmX2.80mmX1.85mm.

LED AlGaInp

: 3.50mmX2.80mmX1.85mm 。

1.2 Features

PLCC4 Package. PLCC4

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.

Available on tape and reel.

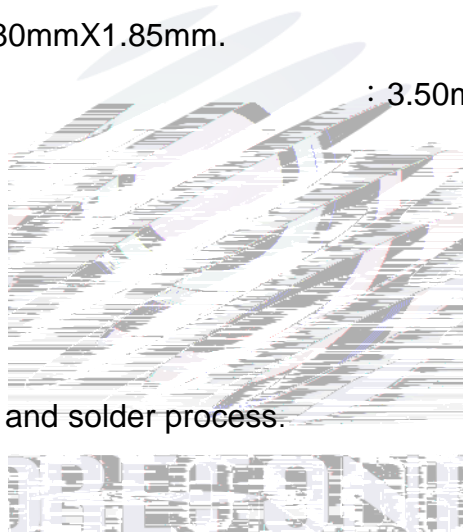
Moisture sensitivity level: Level 2.

Level2

Compliance with RoHS and REACH. 符合RoHS和REACH要求

Qualifications: The product qualification test plan is based on the guidelines of AEC-Q101 Stress Test Qualification for Automotive Grade Discrete Semiconductors

AEC-Q101

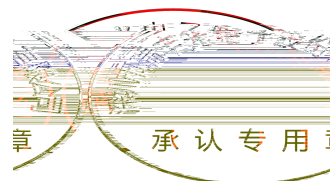


SMT

1.3 Application

Automotive Interior Lighting. 汽 内 照明

Switches. 开关



1.4 Package Dimension

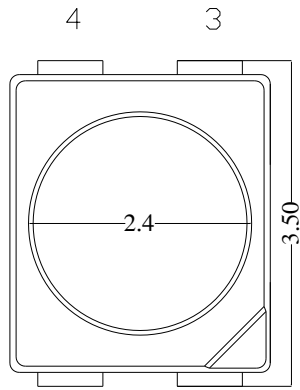


Fig.1-1 Top View

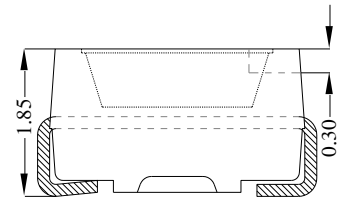


Fig.1-2 Side View

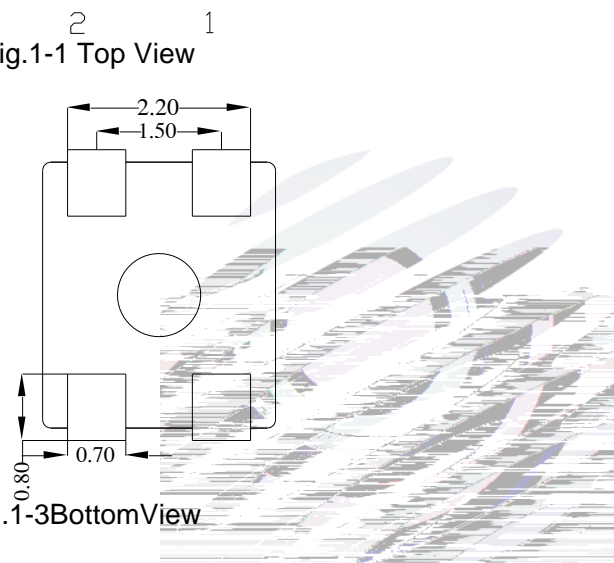


Fig.1-3 Bottom View

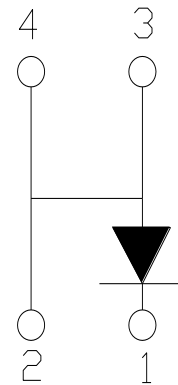


Fig.1-4 Polarity

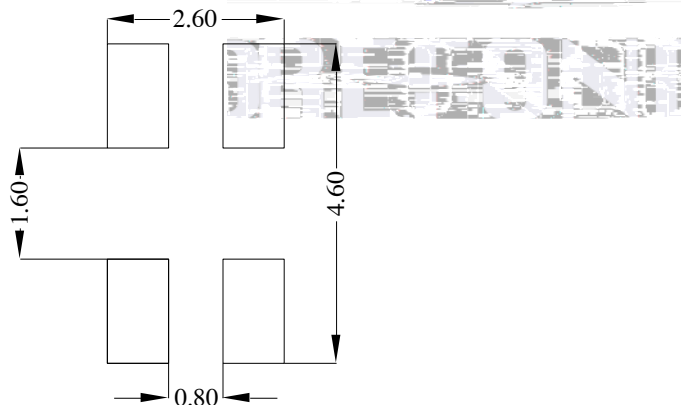
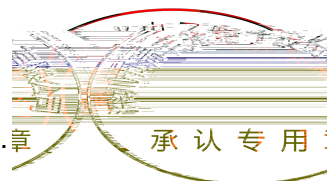


Fig.1-5 Soldering Patterns

Notes

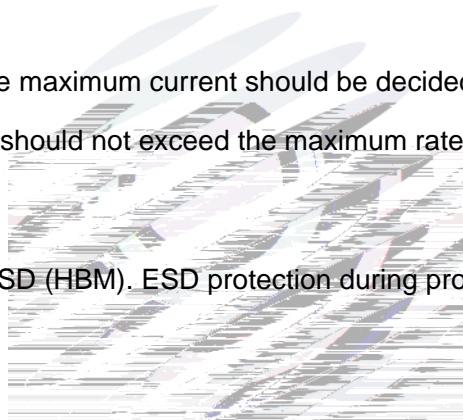
1. All dimensions units are millimeters.
2. All dimensions tolerances are $\pm 0.2\text{mm}$ unless otherwise noted.



0.2

Notes

1. 1/10 Duty cycle, 10ms pulse width. 10ms, 1/10.
2. The above forward voltage measurement allowance tolerance is $\pm 0.1V$.
3. The above color coordinates measurement allowance tolerance is ± 0.005 . ± 0.005 .
4. The above luminous intensity measurement allowance tolerance $\pm 10\%$.
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate. LED
8. ESD yield is over 90% at 2000V ESD (HBM). ESD protection during products handling is needed. 90% LED ESD2000V ,



1.6 Bin Range Of Forward Voltage and Luminous Intensity and Dominant wavelength (IF=50mA) BIN (IF=50mA)

Table 1-3

V _F V	B1	B2	C1	C2	D1	D2
	1.8-1.9	1.9-2.0	2.0-2.1	2.1-2.2	2.2-2.3	2.3-2.4
IV mcd	M1	M2	N1	N2		
	1200-1500	1500-1800	1800-2300	2300-2800		
WD(nm)	F2	G1	G2	H1		

1.7 Typical Optical Characteristics Curves

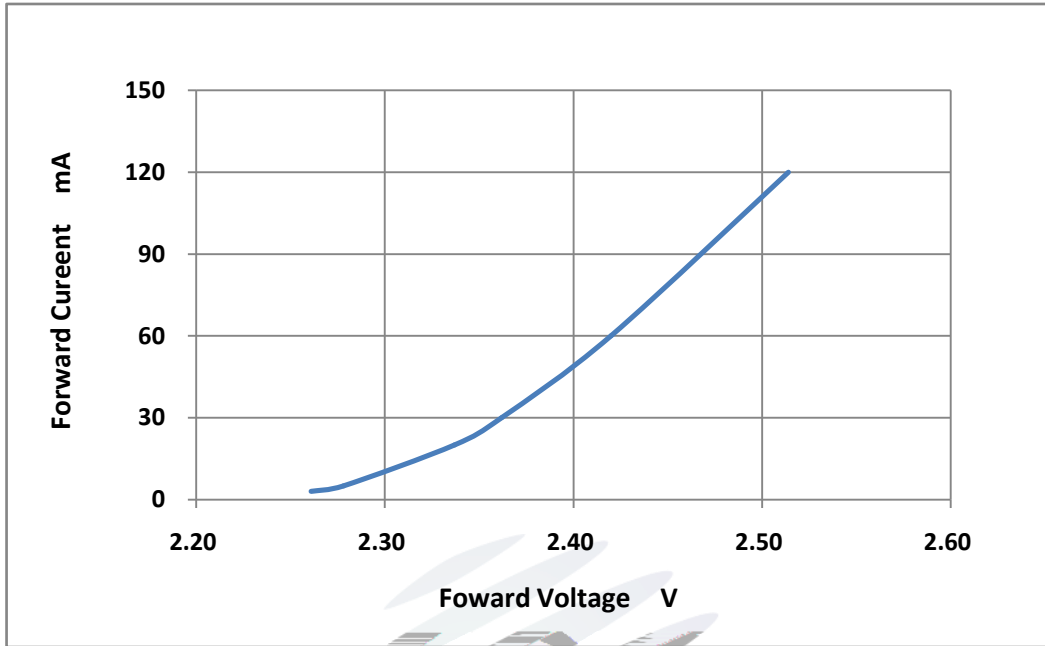


Fig. 1-7 Forward Voltage Vs Forward Current

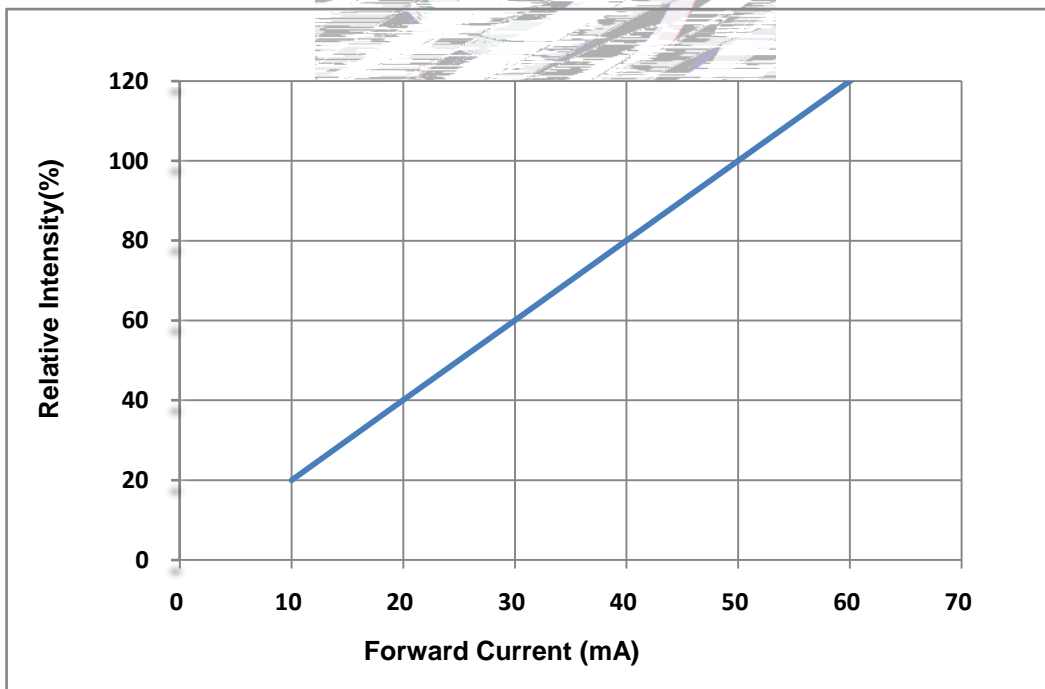
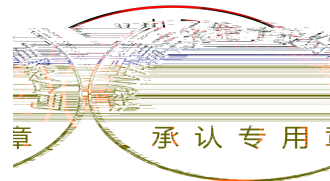


Fig. 1-8 Forward Current Vs Relative Intensity



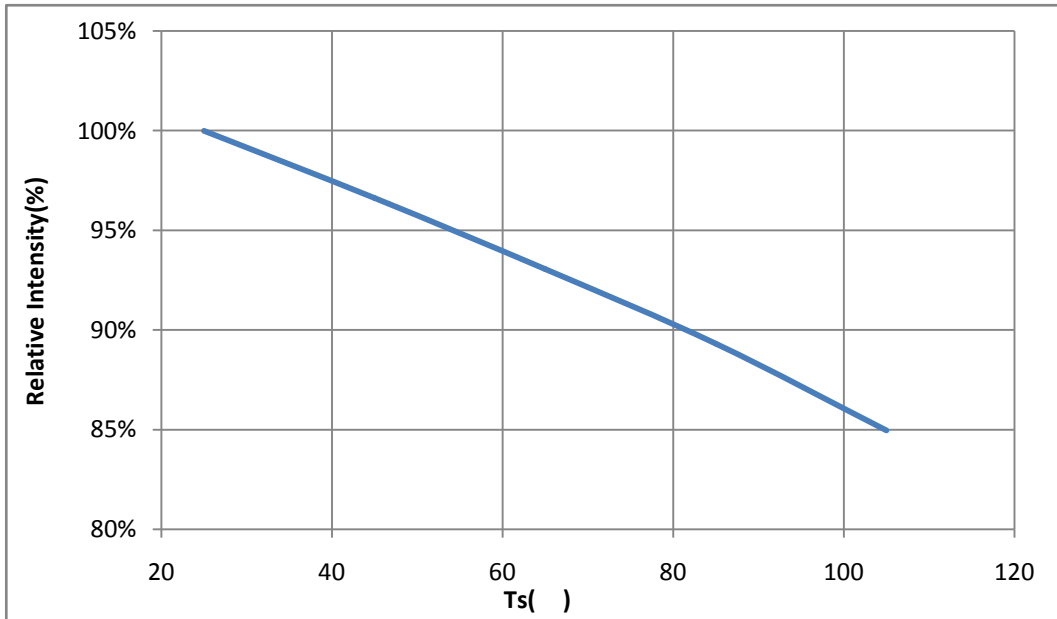


Fig. 1-9 Solder Temperature Vs Relative Intensity

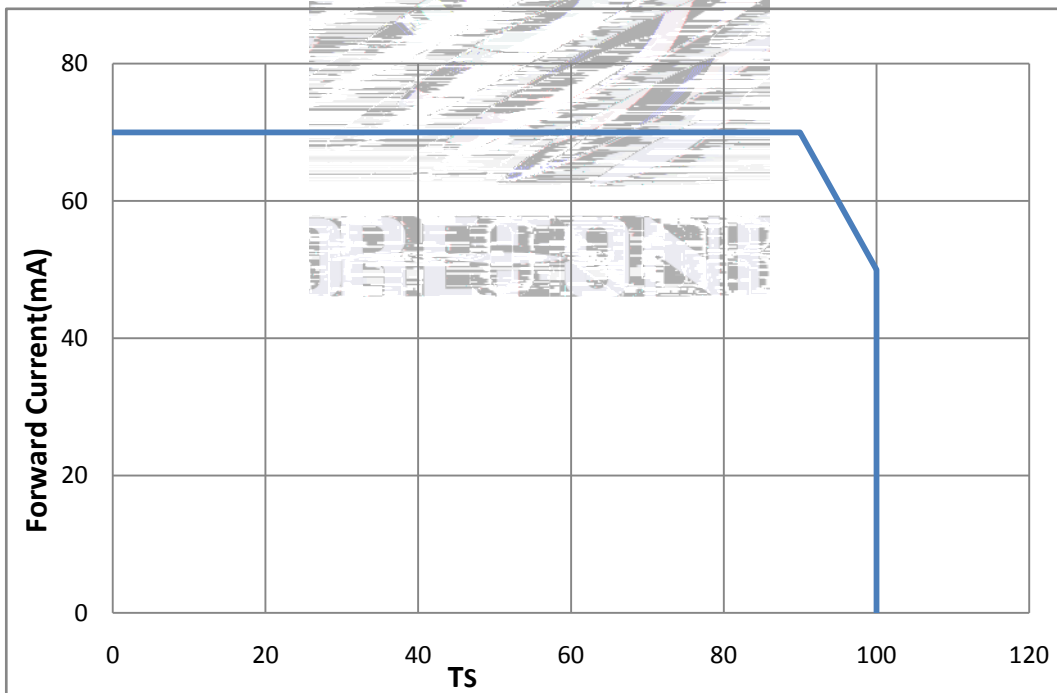
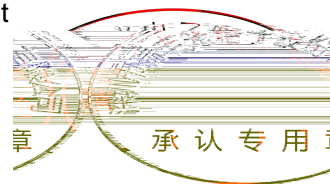


Fig. 1-10 Solder Temperature Vs Forward Current



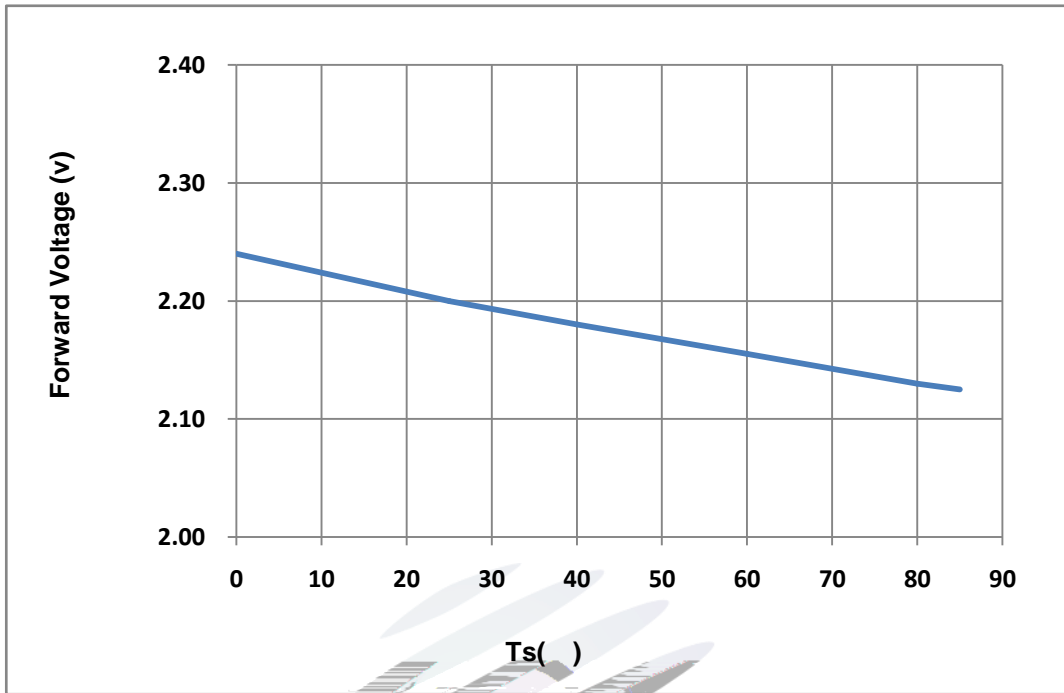


Fig. 1-11 Forward Voltage Vs Solder Temperature

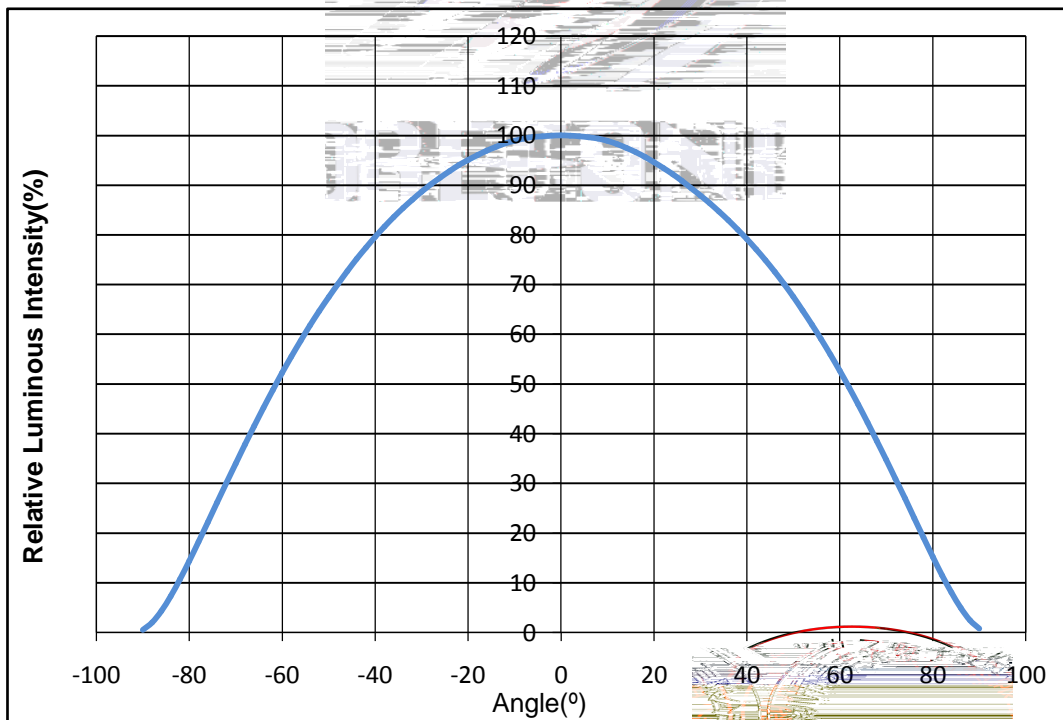


Fig. 1-12 Radiation diagram

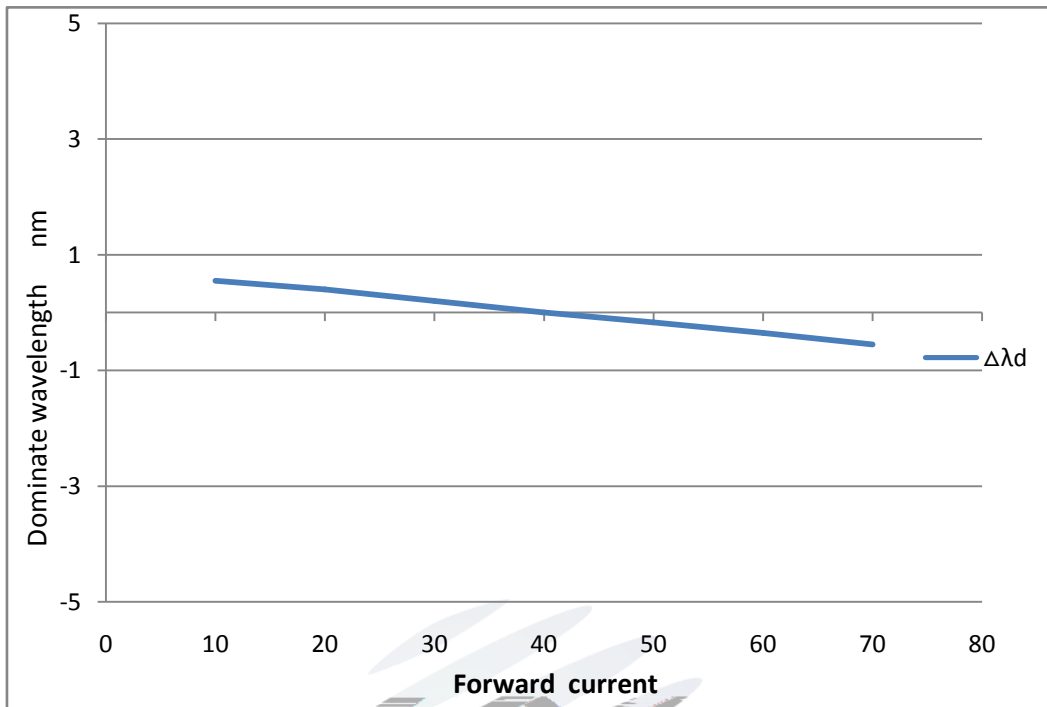


Fig. 1-13 Forward current vs. Dominant wavelength (Ts=25°C)

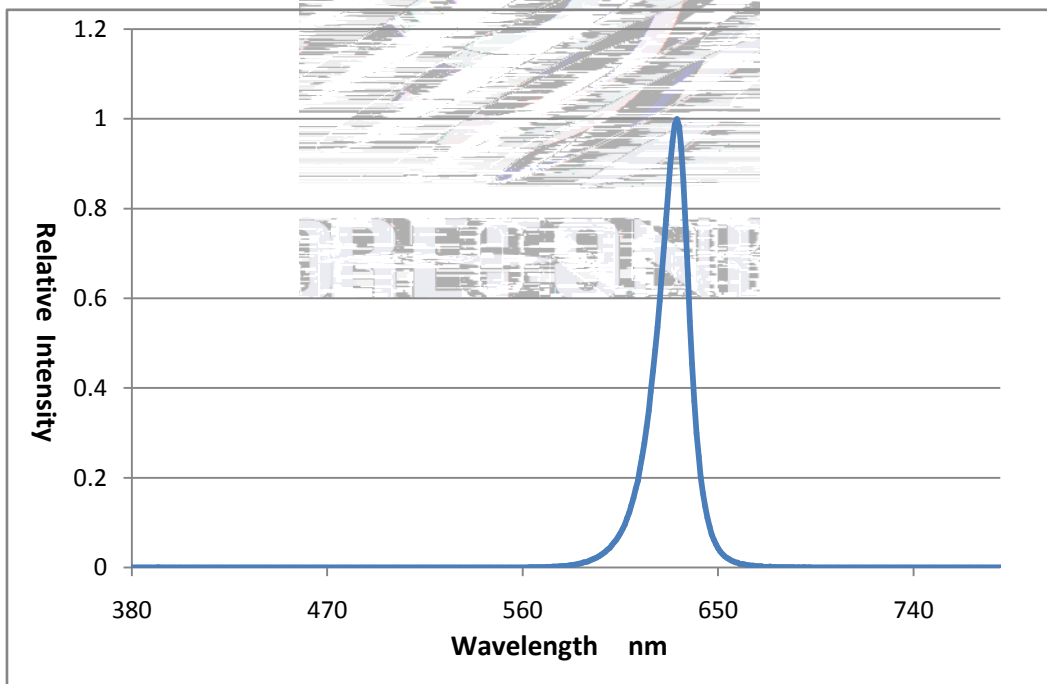
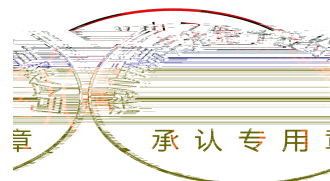


Fig. 1-14 Spectrum Distribution



2. Packaging

2.1 Packaging Specification

Package: 2000pcs/reel. 2000pcs

2.1.1 Carrier Tape Dimension

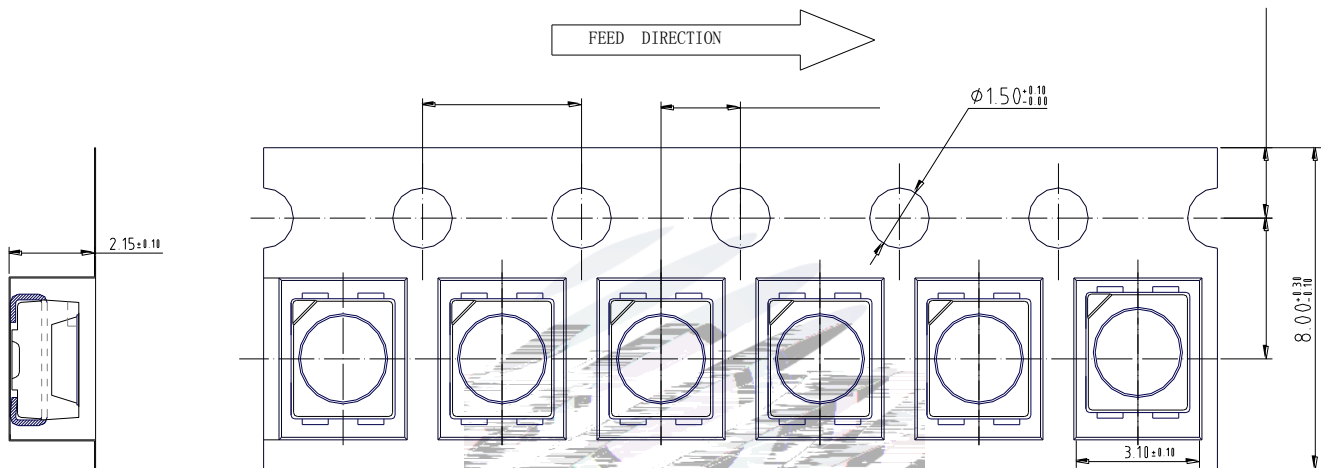


Fig.2-1 Carrier Tape Dimension

2.1.2 Reel Dimension

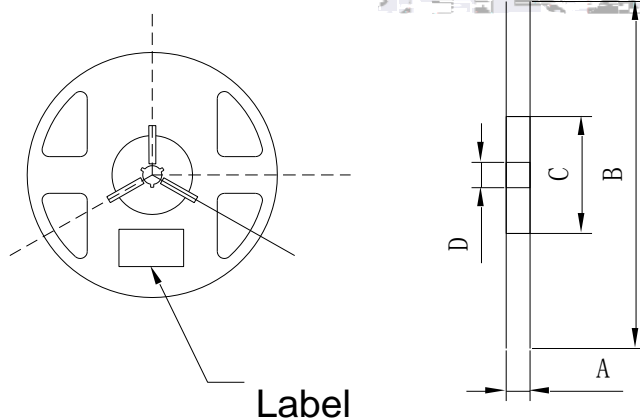


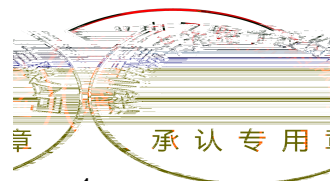
Fig.2-2 Reel Dimension

Table 2-1 Reel Dimension

A	8.0 0.1mm
B	330 1mm
C	100 1mm
D	13.0 0.5mm

Notes

The tolerances unless mentioned ± 0.1 mm. Unit : mm



1

2.1.3 Label Form Specification

Table 2-2 Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code

Fig. 2-3 Label

2.2 Moisture Resistant Packing

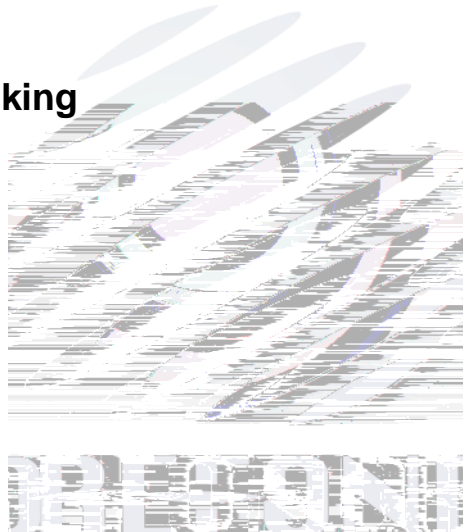


Fig.2-4 Moisture Resistant Packing

High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH I _F =50mA	1000hrs.	20pcs.	0/1
Temperature Humidity Storage	JEITA ED-4701 100 103	T _A =85 R _H =85%	1000hrs.	20pcs.	0/1

2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V _F	I _F =50mA	-	U.S.L*)x1.1
Reverse Current	I _R	V _R = 5V	-	U.S.L*)x2.0
Luminous Flux		I _F =50mA	L.S.L*)x0.7	-

Notes

- 1.U.S.L: Upper standard level L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment was taken under good heat dissipation conditions. when customers applies the LED to the series and parallel circuit, should take consideration of all the factors such as the current, voltage distribution, heat dissipation and others.

LED



LED

3.The technical information shown in the data sheets is limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.

3. SMT Reflow Soldering Instructions SMT 回流焊说明

3.1SMT Reflow Soldering Instructions SMT

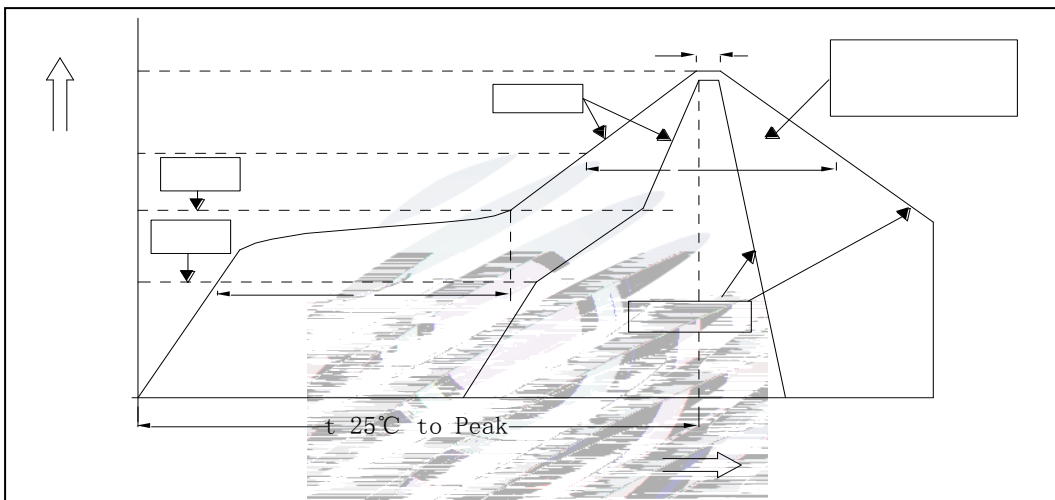


Fig.3-1SMT Reflow Soldering Instructions SMT

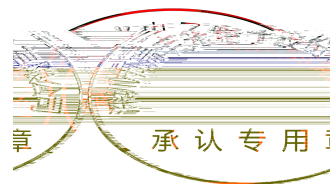
Table 3-1Reflow parameters

Average temperature rise speed	$T_{smax} - T_p$	3 °C/ s Max 3 °C/ s
Preheating: minimum temperature	(T_{smin})	150 °C
Preheating: Max temperature	(T_{smax})	200 °C
Preheating: Time	$T_{smin} - T_{smax}$	60 - 120 60s-120s
Time limited to maintain high temperature: the temperature	(T_L)	217 °C
Time limited to maintain high temperature: The Time	(t_L)	60 Max 60s
Peak /Classification of temperature:	(T_P)	260 °C
Time limit classification of peak temperature time	t_p	10 Max 10s

(T _P)	5 °C	Hold time within 5	30	Max 30s
C with the actual peak temperature (TP)				
Cooling speed			6 °C/	Max 6 °C/ s
25 °C	Needed time from 25 °C to T _p		8	Max 8 minutes

Notes

(1)Reflow soldering should not be done more than twice.



LED

(2) Components should not be mounted on warped (non coplanar) portion of PCB. After soldering, do not warp the circuit board. LED PCB

(3) Do not apply mechanical force or excess vibration during the cooling process to normal temperature after soldering. Do not rapidly cool device after soldering.

4. Handling Precautions

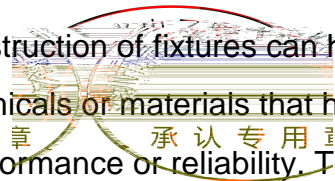
4.1 Handling Precautions

(1) LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating usage material. This is provided for informational purposes only and is not a warranty or endorsement. LED 100PPM.

(2) In order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the total content of Bromine element and Chlorine element in the external materials of the application products is required to be less than 1500PPM. This is provided for informational purposes only and is not a warranty or endorsement. LED LED

900PPM 900PPM
1500PPM.

(3) VOCs (Volatile organic compounds) emitted from materials used in the construction of fixtures can penetrate silicone encapsulants of LEDs and discolor when exposed to heat and photonic energy. The result can be a significant loss of light output from the fixture. Knowledge of the properties of the materials selected to be used in the construction of fixtures can help prevent these issues. Refond advises against the use of any chemicals or materials that have been found or are suspected to have an adverse affect on device performance or reliability. To verify





(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

LED

Table 4-1 Storage

Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours 24
Baking		60 5	-	24hours 24

(8) If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed after unpacking and based on the following condition (65±5) °C for above 24 hours.

60 5

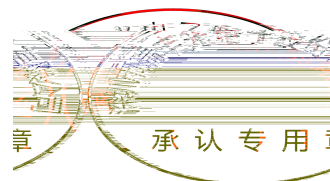
24

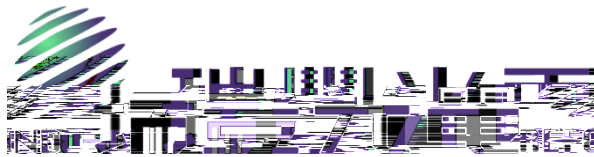
If the package is flatulence or damaged, please notify the sales staff to assist.



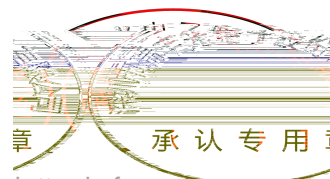
(9) Similar to most Solid state devices; LEDs are sensitive to Electro-Static Discharge (ESD) and Electrical Over Stress (EOS). LED

(10) Other points for attention, please refer to our relevant information.





www.refond.com



Declare

This specification is written both in English and in Chinese and the latter is formal.